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		SPE(Date	C.No. ASDIQ-SPE-081(00) : Jul. 13, 2022	
To:				
	CUSTOMER'S PRO	DDUCT NAME		
	ASDI PRODUCT NA	AME:		
	SPAC6D28N-SERIES			
RECEIPT CONFIRMATION		CONDIT	TIONIAL CONCENT	
UNCONDITION	AL CONSENT	CONDIT	TIONAL CONSENT	
Al	PROVED	CHEC	CKED	
ASDI SIGNATURE				
APPROVED	CHECKED	PREPARED		
Xianglong Li		Jiayin Cai		



Xiamen ASDI Electronics Co.,Ltd.

REV.	DATE	DESCRIPTION	APPROVED	CHECKED	PREPARED
00	Jul. 13, 2022	New release	Xianglong Li	Liang Wang	Jiayin Cai

CAUTION WHEN HANDLING

Before use the products, please read this specification.

CAUTION FOR SAFETY USING

When use the products, be careful to mentioned below for safety using.

CAUTION

*The product should be used within 12 monthes.

Focus on the storage conditions.

Solderability may become weak if it exceeds the period.

*Do not use and store product and store the product in condition of gas corrosion (Salt,Acid,Alkaline).

*The products must be preheated before soldering.

The operating temperature including self-generated heat must be within '-40~+125℃

*Rework by soldering iron; Please keep the mentioned conditions in this specification.

*In case of insert P.C. Board on chassis, do not add mechanical stress to the product.

*Be careful to arrange of non-magnetic field type inductors.

The error may be caused by magnetic field coupling.

*In case handle the products, please use wrist strap for ground static discharge on human body.

The product keeps away from magnet or magnetized things.

*Do not use the product beyond the mentioned conditions in this specification.

*About an application

The products listed on this specification sheet are intended for use in general electronic equipment

(AV equipment, telecommunications equipment, home appliances, amusement equipment, computer equipment, personal equipment, office equipment, measurement equipment, industrial robots) under a normal operation and use condition.

*The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property. Please understand that we are not responsible for any damage or liability caused

by use of the products in any of the applications below or for any other use exceeding the range or conditions set forth in this specification sheet.

1)Aerospace/Aviation equipment
2)Military equipment
3)Seabed equipment
4)Safety equipment
5)Medical equipment

6)Transportation control equipment
7)Power-generation control equipment
which directly endanger human life
8)Atomic energy-related equipment
9)Other applications that are not

considered general-purpose applications

If you intend to use the products in the following applications, please contact our sales office.

Transportation equipment (cars, electric trains, ships, etc.), Public information-processing equipment, Electric heating apparatus / burning equipment, Disaster prevention/crime prevention equipment

When using this product in general-purpose applications, you are kindly requested to take into consideration securing protection circuit/equipment or providing backup circuits, etc., to ensure higher safety.

Xiamen ASDI Electronics Co.,Ltd.

DWG.No.
ASDIQ-SPE-081(00)

ISSUE

CUSTOMER	ASDI PART No.	CUSTOMER'S DWG NO.
Each Corporation	SPAC6D28N-SERIES	

1.SCOPE

Power source inductor for mobile devices such as HDDs, DVCs,DSCs,mobile display panels, portable game devices, compact power supply LCDs, other DC to DC converters

2.INDEX _____

Listed item	Attachment&Tables	Page
1.Features	Please see (1)	3/6
2.Dimensions	Please see (2)	3/6
3.Recommendend Land pattern	Please see (3)	3/6
4.Part Numbering	Please see (4)	3/6
5.Electrical Specifications	Please see (5)	3/6
6.Reliability Tests	Please see (6)	4/6
7.Soldering	Please see (7)	6/6
8.Packaging Information	Please see (8)	6/6
9.Note	Please see (9)	6/6
10.Standard test conditions		
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3.Manufacturing Location

China

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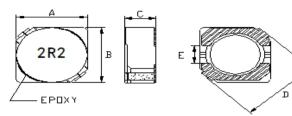
(1)Features

This specification applies Low Profile Power Inductors. 100% Lead(Pb) & Halogen-Free and RoHS compliant.





(2)Dimensions



Series	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
SPAC6D28N	6.7±0.3	6.7±0.3	3.0MAX	9.5MAX	2.0

(3)Recommendend Land pattern

H(mm)	l(mm)	K(mm)
7.3 TYP	2.6 TYP	2.0 TYP

Recommended Land Pattern



(4)Part Numbering

SPAC	6D28	N	-	1R0	M
Α	В	С		D	E
A: Series					

B: Dimension

C: Control S/N

D: Inductance 1R0=1.0µH E: Inductance Tolerance $M=\pm 20\%;$

(5)Electrical Specification

Table 1

ASDI Part Number	Inductance (µH)	Tolerance (%)	Test Frequency	DCR (Ω) Max	I sat (A)	I rms (A)
SPAC6D28N-1R0M	1.00	±20%	100kHz/0.25V	0.020	3.50	2.95
SPAC6D28N-1R5M	1.50	±20%	100kHz/0.25V	0.022	3.45	2.90
SPAC6D28N-2R2M	2.20	±20%	100kHz/0.25V	0.026	3.45	2.80
SPAC6D28N-3R3M	3.30	±20%	100kHz/0.25V	0.031	2.80	2.35
SPAC6D28N-4R7M	4.70	±20%	100kHz/0.25V	0.038	2.56	2.40
SPAC6D28N-6R8M	6.80	±20%	100kHz/0.25V	0.052	2.00	1.65
SPAC6D28N-100M	10.0	±20%	100kHz/0.25V	0.065	1.60	1.35
SPAC6D28N-150M	15.0	±20%	100kHz/0.25V	0.086	1.40	1.20
SPAC6D28N-220M	22.0	±20%	100kHz/0.25V	0.135	1.10	0.95
SPAC6D28N-330M	33.0	±20%	100kHz/0.25V	0.165	0.95	0.80
SPAC6D28N-470M	47.0	±20%	100kHz/0.25V	0.300	0.80	0.65
SPAC6D28N-560M	56.0	±20%	100kHz/0.25V	0.385	0.65	0.55
SPAC6D28N-680M	68.0	±20%	100kHz/0.25V	0.425	0.60	0.50
SPAC6D28N-101M	100	±20%	100kHz/0.25V	0.620	0.50	0.40

Note:

Isat: Based on inductance change (\triangle L/L0: \le -35%) @ ambient temp. 25°C

Irms: Based on temperature rise (△T: 40°C typ.)

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ASDL	Flectronics Co. Ltd		

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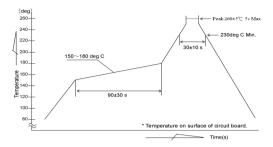
Resistance to flexure substrate No damage Substrate size: 100x4 Substrate material: gla Solder cream thickness The test samples shall testing board and by the	or equivalent, 100kHz, 3227 or equivalent ance shall be taken at
Storage temperature	227 or equivalent
Resistance to flexure substrate Adhesion of Terminal electrode Adhesion of Terminal electrode Resistance to flexure substrate Adhesion of Terminal electrode Resistance to flexure substrate Adhesion of Terminal electrode Resistance to flexure substrate Inductance change: Within±10% Resistance to flexure substrate Adhesion of Terminal electrode Resistance to flexure substrate Adhesion of Terminal electrode Resistance to flexure substrate flexure substrate flexure substrate material: glissolder cream thickness flexure substrate flexure	227 or equivalent
4 Inductance (L) 5 DC Resistance 6 Temperature characteristics Inductance change: Within±20% The test samples shall testing board and by the flexure substrate 8 Adhesion of Terminal electrode 8 Adhesion of Terminal electrode 9 Resistance to Inductance change: Within±10% 8 Resistance to Inductance change: Within±10% 9 Resistance to Inductance change: Within±10% 1 Inductance change: Within±10% 2 Inductance change: Within±10% 3 Inductance change: Within±10% 4 Inductance change: Within±10% 5 Inductance change: Within±10% 6 Inductance change: Within±10% 8 Inductance change: Within±10% 9 Inductance change: Within±10% 8 Inductance c	227 or equivalent
Within the specified tolerance DC Ohmmeter: HIOKIS Measurement of induct temperature rang within With reference to induct temperature rang within With reference to induct temperature rang within the specified tolerance with the specified tolerance of the specifi	ance shall be taken at
Temperature characteristics Inductance change: Within±20% Measurement of induct temperature rang within with reference to induct the part of the arrow indicating test board by the reflection of flexure substrate No damage Resistance to Substrate size: 100x4 Substrate material: glis Solder cream thickness substrate material: glis Solder cream thickness from the control of the substrate size: 100x4 Substrate material: glis Solder cream thickness from the control of the substrate size: 100x4 Substrate material: glis Solder cream thickness from the control of the substrate size: 100x4 Substrate material: glis Solder cream thickness from the control of the	ance shall be taken at
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Resistance to flexure substrate No damage Resistance to flexure substrate Substrate size: 100x4 Substrate material: gls Solder cream thickness The test samples shall testing board and by the string board and by the string board and by the solder cream thickness Applied force: 10 N to Duration: 5s Solder cream thickness The test samples shall board by the reflow. Then it shall be submit conditions. Frequency: 10-55Hz Resistance to Inductance change: Within±10% No abnormality observed in appearance.	etance value at+20 e calculated. ance shall be taken at n–40℃ to +125℃. etance value at+20
Adhesion of Terminal electrode Shall not come off PC board. Applied force: 10 N to Duration: 5s Solder cream thickness The test samples shall board by the reflow. Then it shall be submit conditions. Frequency: 10-55Hz Total Amplitude: 1.5mr acceleration 196m/S2	Board Board Board Board Board Board Board A5±2 DX1.0 Bass epoxy-resin Color 15 A4.0
board by the reflow. Then it shall be submit conditions. Frequency: 10-55Hz Total Amplitude: 1.5mr 9 Vibration No abnormality observed in appearance acceleration 196m/S2	be soldered to the e reflow. N, 5 s X and Y directions.
1min. Time: 2 hours each in Recovery: At least 2hrs standard condition afte the measurement withi	n (May not exceed to 55Hz to 10Hz for X,Y, and Z Direction. of recovery under the r the test, followed by
The test samples shall then immersed in molte below. At least 90% of surface of terminal electrode is covered by new solder. At least 90% of surface of terminal Solder temperature: 24 Time: 5±1.0 sec. Immersion depth: All si terminal shall be immer.	be dipped in flux, and en solder as shown in n containing rosin 25% 5±5℃ des of mounting

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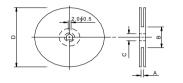
No.	Test item	Performance	Test details		
11	Resistance to soldering		The test sample shall be exposed to reflow oven at 230±5℃ for 40 seconds, with peak temperature at 260±5℃ for 5 seconds,2 times. Test board thickness: 1.0mm Test board material: glass epoxy-resin		
12	Thermal shock		The test samples shall be soldered to the test board by the reflow. The test samples shall be placed at specified temperature for specified time by step 1 to step 4 as shown below in sequence. The temperature cycles shall be repeated 100 cycles . Phase Temperature(©) Time(min.) 1 -40±3© 30±3 2 RoomTemp Within 3 3 85±2© 30±3 4 RoomTemp Within 3		
13	Damp heat life test	Inductance change: Within±10% No abnormality observed in appearance.	Test Method and Remarks The test samples shall be soldered to the test board by the reflow. The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below. Temperature: 60±2°C Humidity: 90~95%RH Time: 500+24/-0 hrs		
14	Loading under damp heat life test		The test samples shall be soldered to the test board by the reflow. The test samples shall be placed in thermostatic oven set at specified temperature and humidity and applied the rated current continuously as shown in below. Temperature: 60±2°C Humidity: 90~95%RH Applied current: Rated current Time: 500+24/-0 hrs		
15	Low temperature life test		The test samples shall be soldered to the test board by the reflow. After that, the test samples shall be placed at test conditions as shown in below. Temperature:-40±2°C Time:500+24/-0 hrs		
16	Loading at high temperature life test		The test samples shall be soldered to the test board by the reflow. Temperature: 85±2°C. Applied current: Rated current Time: 500+24/-0 hrs.		

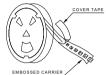
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(7)Soldering



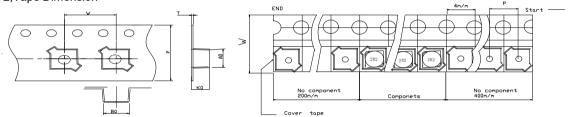
(8)Packaging Information 8-1,Reel Dimension





Туре	A(mm)	B(mm)	C(mm)	D(mm)
SPAC6D28N	16.4±0.2	100±4.0	13.2±0.2	330±2.0

8-2, Tape Dimension



Туре	Ao(mm)	Bo(mm)	Ko(mm)	P(mm)	W(mm)	t(mm)
SPAC6D28N	7.3±0.1	7.3±0.1	3.2±0.1	12.0±0.1	16±0.3	0.4±0.05

8-3, Packaging Quantity

Туре	Chip / Reel		
SPAC6D28N	1000		

(9)Note

·Storage Conditions

To maintain the solderability of terminal electrodes:

- 1. ASDI products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 2. Temperature and humidity conditions: Temperature: 5 to 30deg.C, Humidity: 75% Max.
- 3. Recommended products should be used within 12 months form the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- ·Transportation
- 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
- 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

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单击下面可查看定价,库存,交付和生命周期等信息

>>ASDI